



Material Content Data Sheet



Sales Product Name		TLE42754E		Issued		22. January 2018		
MA#		MA001131652						
Package		PG-SSOP-14-2		Weight*		83.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.311	3.96	3.96	39639	39639
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		412	
	non noble metal	iron	7439-89-6	0.689	0.82		8248	
wire	non noble metal	copper	7440-50-8	27.978	33.49	34.36	334911	343674
	noble metal	gold	7440-57-5	0.131	0.16	0.16	1566	1566
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.12		1151
encapsulation	plastics	epoxy resin	-	4.421	5.29		52925	
	inorganic material	silicondioxide	60676-86-0	43.540	52.13	57.54	521192	575268
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11685	11685
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9189	9189
glue	plastics	epoxy resin	-	0.396	0.47		4745	
	noble metal	silver	7440-22-4	1.189	1.42	1.89	14234	18979
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com